2SA1123

Silicon PNP epitaxial planer type

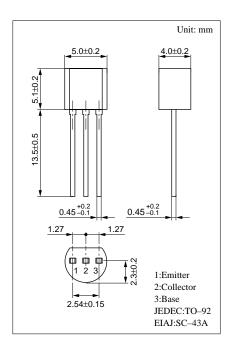
For low-frequency high breakdown voltage amplification Complementary to 2SC2631

Features

- Satisfactory foward current transfer ratio h_{FE} collector current I_C characteristics.
- High collector to emitter voltage V_{CEO}.
- Small collector output capacitance Cob.
- Makes up a complementary pair with 2SC2631, which is optimum for the pre-driver stage of a 20 to 40W output amplifier.

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-150	V
Collector to emitter voltage	V_{CEO}	-150	V
Emitter to base voltage	V_{EBO}	-5	V
Peak collector current	I_{CP}	-100	mA
Collector current	I_{C}	-50	mA
Collector power dissipation	P_{C}	750	mW
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	−55 ~ +150	°C



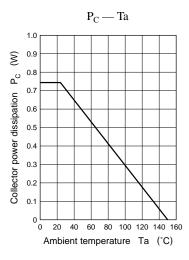
Electrical Characteristics (Ta=25°C)

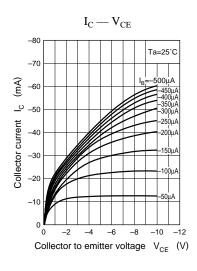
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I _{CBO}	$V_{CB} = -100V, I_E = 0$			-1	μΑ
Collector to emitter voltage	V _{CEO}	$I_C = -0.1 \text{mA}, I_B = 0$	-150			V
Emitter to base voltage	V _{EBO}	$I_{\rm E} = -10\mu A, I_{\rm C} = 0$	-5			V
Forward current transfer ratio	h _{FE} *	$V_{CE} = -5V, I_{C} = -10mA$	130		450	
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = -30 \text{mA}, I_B = -3 \text{mA}$			-1	V
Transition frequency	f_T	$V_{CB} = -10V$, $I_E = 10mA$, $f = 200MHz$		200		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10V, I_E = 0, f = 1MHz$			5	pF
Noise voltage	NV	$V_{CE} = -10V, I_C = -1mA, G_V = 80dB$		150	300	mV
		$R_g = 100k\Omega$, Function = FLAT				

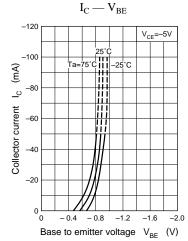
*hFE Rank classification

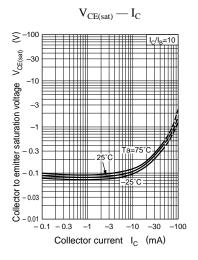
Rank	R	S	T
h_{FE}	130 ~ 220	185 ~ 330	260 ~ 450

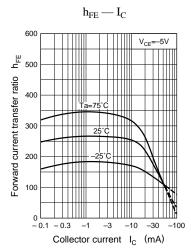
Transistor 2SA1123

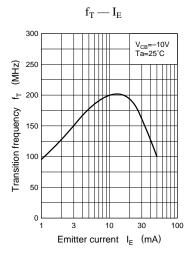


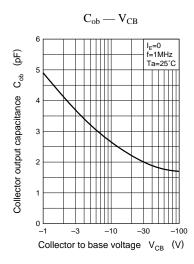












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